

INFN and University of Perugia

TCAD model of radiation damage at High Fluence HL-LHC silicon detectors

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Outline

- ✓ INFN and University of Perugia are involved in WP7.
- ✓ 7.2 TCAD simulations:
 - development of a TCAD model for the description of radiation damage in silicon detectors valid up to the particle fluences expected in the inner layers of the HL-LHC vertex detectors
- ✓ Main goal synopsis:
 - i. extension of the TCAD model to simulate the effects of radiation damage on silicon devices, up to now able to reproduce the sensor behaviour at the fluences at LHC operation (1×10^{15} n/cm²);
 - ii. development of bulk damage as well as interface trap states build up modelling for a particle fluence $> 2 \times 10^{16}$ n/cm², expected at the end of HL-LHC operations in the inner layers of the pixel systems of ATLAS and CMS.
- ✓ Participants: G.M. Bilei (INFN PG staff), D. Passeri (UniPG staff), F. Moscatelli (INFN PG and CNR-IMM staff), E. Fiandrini (UniPG staff), A. Morozzi (UniPG PhD student).

Background: “University of Perugia” model

- ✓ Hierarchical approach based on increasing number of deep-level recombination centres / trap states.
- ✓ Comprehensive modelling of device behaviour of with fluence:
 - depletion voltage, leakage current (α), “double peak” shaped electric field, charge collection efficiency,...
- ✓ Meaningful and physically sounded parametrization.
- ✓ Three levels with donor removal and increased introduction rate (to cope with direct inter-defect charge exchange – numerically overwhelmed effect).
- ✓ n type and p type substrate
- ✓ Suitable for fluences up to 10^{15} cm⁻² 1 MeV neutrons.

New “University of Perugia” model

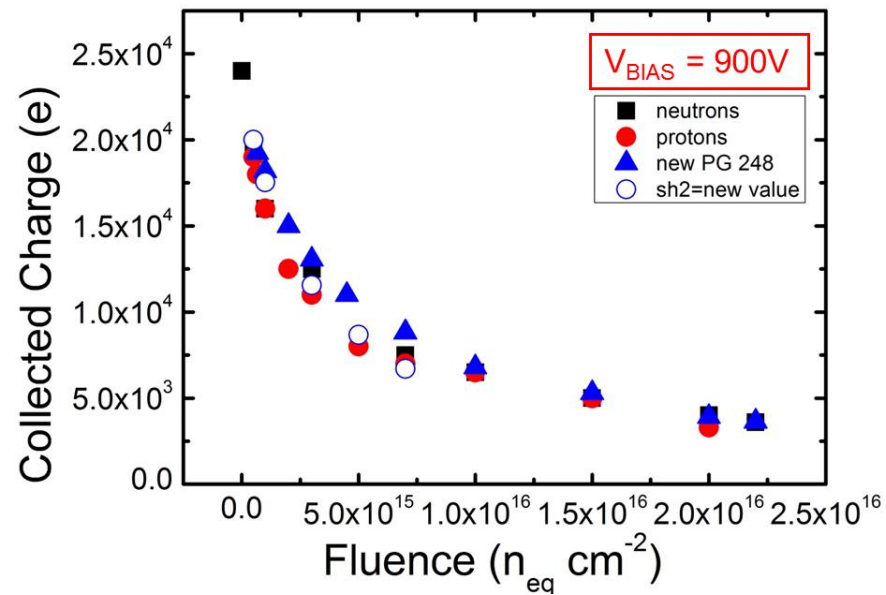
- ✓ Extend the predictive capabilities to HF HL-LHC radiation damage levels (e.g. fluences $> 2.0 \times 10^{16} \text{ cm}^{-2}$ 1 MeV neutrons).
- ✓ Keep low the number of traps (e.g. fitting parameters).
- ✓ New effects (e.g. charge multiplication \leftarrow avalanche effects).
- ✓ Physically grounded approach.
- ✓ No over-specific modelling (one model fits all...).
- ✓ Capture cross-section variations (σ_n, σ_p), keeping the same (already characterized) defects: energy levels, introduction rates, ...
- ✓ Predictive capabilities @ Φ , @T, @V_{bias}, ... (e.g. device independent).

Work plan: simulations

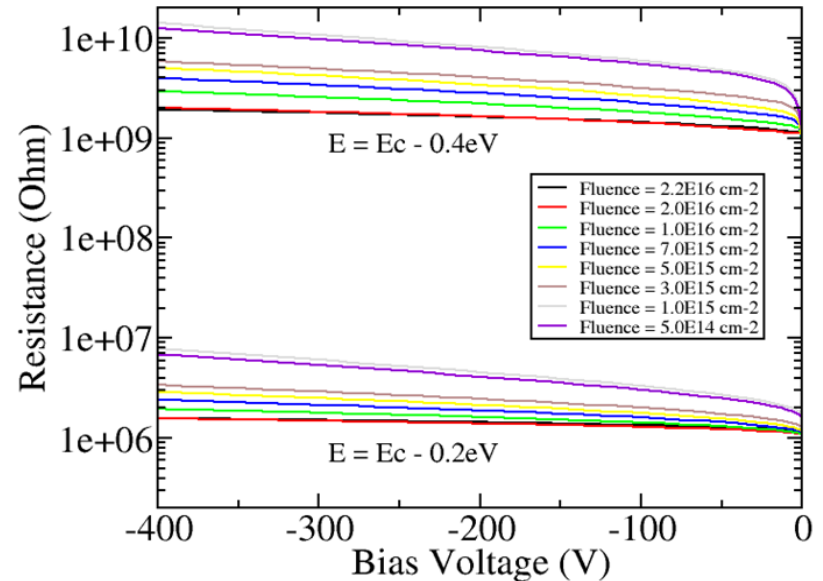
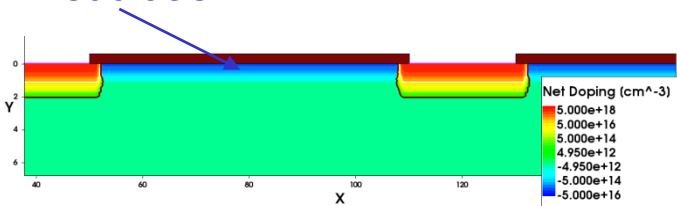
- ✓ **Bulk** radiation damage modelling:
 - extension of the three-level UniPG modelling (capture cross section, charge multiplication, avalanche effects).
- ✓ **Interface** radiation damage modelling:
 - oxide fixed charge and interface trap state @fluence;
 - systematic study of acceptor/donor states at different energies.
- ✓ Technology (process) dependent effect -> deep level parameterization, oxide charge density, interface trap energy and density, cross sections (e/h), trap type (acceptor or donor).
- ✓ Comparison with literature data/dedicated measurements in terms of static parameters (R, C) and charge collection properties.
- ✓ Comprehensive modelling (bulk + interface, 2D/3D).

- ✓ Simulations vs. measurements.
- ✓ Charge collection as a function of radiation fluences at $T=248\text{K}$, $V_{\text{BIAS}}=900\text{V}$ [1].

[1] Affolder et al., NIM A, Vol. 623 (2010).



- ✓ Interstrip resistance as a function of bias voltage at different radiation fluences.
- ✓ Effect of the acceptor Si/SiO₂ trap state – accumulation layer modulation.



Work plan: measurements

- ✓ Measurements on dedicated test structures e.g. gated diodes, MOS capacitors and MOSFETs on p-spray/different substrates.
- ✓ Different technologies (e.g. FBK, IMM, ...).
- ✓ High-Frequency and Quasi-Stationary C , MOSFET V_{TH} and I-V characteristics, ...
- ✓ Irradiation campaign with gammas, x-ray and protons/neutrons at very high fluences ($2 \times 10^{16} n_{eq}/cm^2$).
- ✓ Measurements after irradiation -> trap parameter extraction, TCAD model validation.
- ✓ Predictive application of the model -> sensor design and optimization.
- ✓ Deliverable D7.4 TCAD model radiation damage (month 46).
- ✓ TCAD simulation activity already started (13th Pisa meeting poster presentation, NSS 2015 abstract submitted).

Backup

"University of Perugia" model (2)

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Numerical Simulation in p-Type Silicon Detectors

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Abstract—In this paper, the radiation-damaged silicon detector models employed in the actual physical picture at a first-principle (i.e., derived from a hierarchical and suitable approximation of the behavior of silicon device in a three deep-level trapping of Shockley–Read–Hall theory) the radiation is considered.

Index Terms—Radiation

SOLID-STATE semiconductor devices are widely used in the detectors, due to a number of advantages over more conventional conventional technology. The detector fabrication technology can be integrated on a fine spatial resolution, and the detector operating environment depends on a number of factors. The detector is kept under strict control to avoid a full depletion of the detector, which raises significant concerns. The detector is assumed and to occur, the detector reliability is an issue as induced by the incoming radiation. Hence, despite their

Abstract—In the framework of the adoption of p-type substrates has been used to improve the radiation hardness of silicon detectors. The fluence of 1×10^{16} n/cm².

In this work two numerical simulation models for p-type and n-type silicon detector are presented. The analysis of the variation of the leakage current density (J_{leak}), the leakage current density efficiency as a function of the fluence is presented. The results are compared with the Synopsys T-CAD device simulator. The characteristics of irradiated detectors have been compared with experimental measurements extracted from a very good agreement.

The predicted behaviour of p-type silicon detector up to 10^{16} n/cm² shows better detection efficiency and full depletion of the detector material, while comparable behavior of leakage current density.

Index Terms—Device simulation, radiation damage effects.

I. INTRODUCTION

IN RECENT years there has been a significant increase in the radiation tolerance of detectors. The increase of detector energy physics (HEP) experiments, the increase of accelerators energy and the Large Hadron Collider (LHC) at CERN, which is graded to a luminosity of 10^{35} cm⁻² s⁻¹, the expected radiation fluence at distance $R = 4$ cm from the impact point is 10^{16} n/cm². This fluence is equivalent to 10^{16} 1 MeV neutron equivalent neutrons. The detector will require more radiation-tolerant

THE RADIATION DAMAGE MODEL FOR P-TYPE

Level	Ass.	$\sigma_{n,p}$ (cm ²) Exp.[2]	σ_n (cm ²)	σ_p (cm ²)	η (cm ⁻¹)
Ec-0.42eV	VV ^(-/0)	$2 \cdot 10^{-15}$	2×10^{-15}	2×10^{-14}	1.613
Ec-0.46eV	VVV ^(-/0)	$5 \cdot 10^{-15}$	5×10^{-15}	5×10^{-14}	0.9
Ev+0.36eV	CiOi	2.5×10^{-15}	2.5×10^{-14}	2.5×10^{-15}	0.9

TABLE II

THE THREE LEVELS RADIATION DAMAGE MODEL FOR N-TYPE

Level	Ass.	$\sigma_{n,p}$ (cm ²) Exp.[2,9]	σ_n (cm ²)	σ_p (cm ²)	η (cm ⁻¹)
Ec-0.42eV	VV ^(-/0)	2×10^{-15}	2×10^{-15}	1.2×10^{-14}	13
Ec-0.50eV	VVO(?)	5×10^{-15}	5×10^{-15}	3.5×10^{-14}	0.08
Ev+0.36eV	CiOi	2.5×10^{-15}	2×10^{-18}	2.5×10^{-15}	1.1

[1] D. Passeri, I. ...
Radiation D...

[2] M. Petasecca, F. Moscatelli, D. Passeri, and G. U. Pignatelli, *Numerical Simulation of Radiation Damage Effects in p-Type and n-Type FZ Silicon Detectors*, IEEE Trans. on Nuclear Science, vol. 53, no. 5, October 2006.